

EP579-1

Low density epoxy paste

Trelleborg EP579-1 is a two component, low density, epoxy paste designed for epoxy board bonding and repair. It is easily processable and characterized by good mechanical properties and heat stability.

Features & Benefits

- Excellent machinability
- Low Slump
- Low density
- Low porosity
- Good mechanical properties
- High heat stability

Applications

- EP579-1 is designed for epoxy board bonding and repair.

Product Sizes

EP579-1 is available in a 3.5 kg kit.



Storage

Adhesive EP579-1 and hardener EP579-1 should be stored in original containers at a temperature between 15 and 25 °C. The product may crystallize during storage. If crystallized, warm to 55 - 65 °C until dissolution, then mix well. Both components, if stored in the specified conditions, have a shelf life of 12 months from the date of production.

Health & Safety

Eye protection and gloves should be worn when working with Trelleborg EP579-1.

Please refer to the Trelleborg MSDS.

PHYSICAL PROPERTIES

Product	EP579-1 Adhesive	EP579-1 Hardener	Mixture
Material	Epoxy formulation	Amine formulation	Epoxide
Aspect	Paste	Liquid	Paste
Colour	Blue	Blue	Blue
Mix Ratio (pbw)	100	12	
Density	660 kg/m ³	970 kg/m ³	
Viscosity	Paste		Paste
Pot Life* (200 g)			90 minutes
Gel Time* (200 g)			100 minutes
Curing (1 mm/20 °C)			5 hrs
Curing (1 mm/60 °C)			1 hr
Exotherm Peak			88 °C

*data measured at 20 °C

MECHANICAL PROPERTIES		
Shore Hardness	70 D	ISO 868
Flexural Strength	32 MPa	ISO 178
Flexural Modulus	2,400 MPa	ISO 178
Tensile Strength	15.0 MPa	ISO 527-1
Deformation at Break	4.0 %	ISO 527-1
Compressive Strength	24.0 MPa	ISO 604
Linear Shrinkage*	0.04 %	Internal
HDT	135 °C	DSC

* sample 500 x 50 x 10 mm

Processing Guidelines

Preparation of Substrates

Read the Material Safety Data Sheet before use.

Substrate surfaces must be cleaned and dried to remove traces of dust, dirt, oils or release agent before applying EP579-1. If necessary, degrease with 1-bromopropane or other suitable solvent. Models, moulds and parts to be assembled must withstand the recommended post-cure cycle temperature.

Mixing and Application

Adhesive EP579-1 must be mixed with hardener EP579-1 at room temperature (20 – 25 °C) in the exact mix ratio indicated. Initially mix for 4 – 5 minutes until the paste is consistent.

For gluing and repair of epoxy boards intended for applications at elevated temperatures, the use of vacuum is recommended to avoid the retention of voids.

Polymerization and Post-Curing

A full cure is obtained after 72 hours at 20 °C but to allow the material to reach its highest thermal stability, a thermal cycle of 4 hours at 120 °C (or higher) is recommended.

Contact Us

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